

±1°C Fully automatic Nickel and Gold Plating Cleaning Machine

Model: SA-NAGP-48LS

SA-NAGP-48LS features durable imported materials to adapt to acidic corrosive working conditions. It adopts fully automatic operation to deliver stable cleaning performance for wafers after nickel and gold plating. The professional constant temperature system ensures precise temperature control. All electrical parts are treated with anti-corrosion technology. Compatible with industrial management standards, it runs safely and reliably to meet sophisticated semiconductor production requirements.



Feature

- Long-time Acidic Corrosion Resistant
- Double-layer Leak-proof
- Fully Automatic
- Precise Temperature Control
- ISO9001 Quality Assurance

Application

- Wafer Front-End Cleaning
- Photolithography Cleaning
- Etch Post-Cleaning
- Thin Film Cleaning
- Back-End Packaging

Specifications:

Parameter	Descriptions
Temperature Control Accuracy	±1°C
Control Part	PLC and HMI